

IWR1443BOOST


PROC010

REVISIONS
SEE SHEET 2

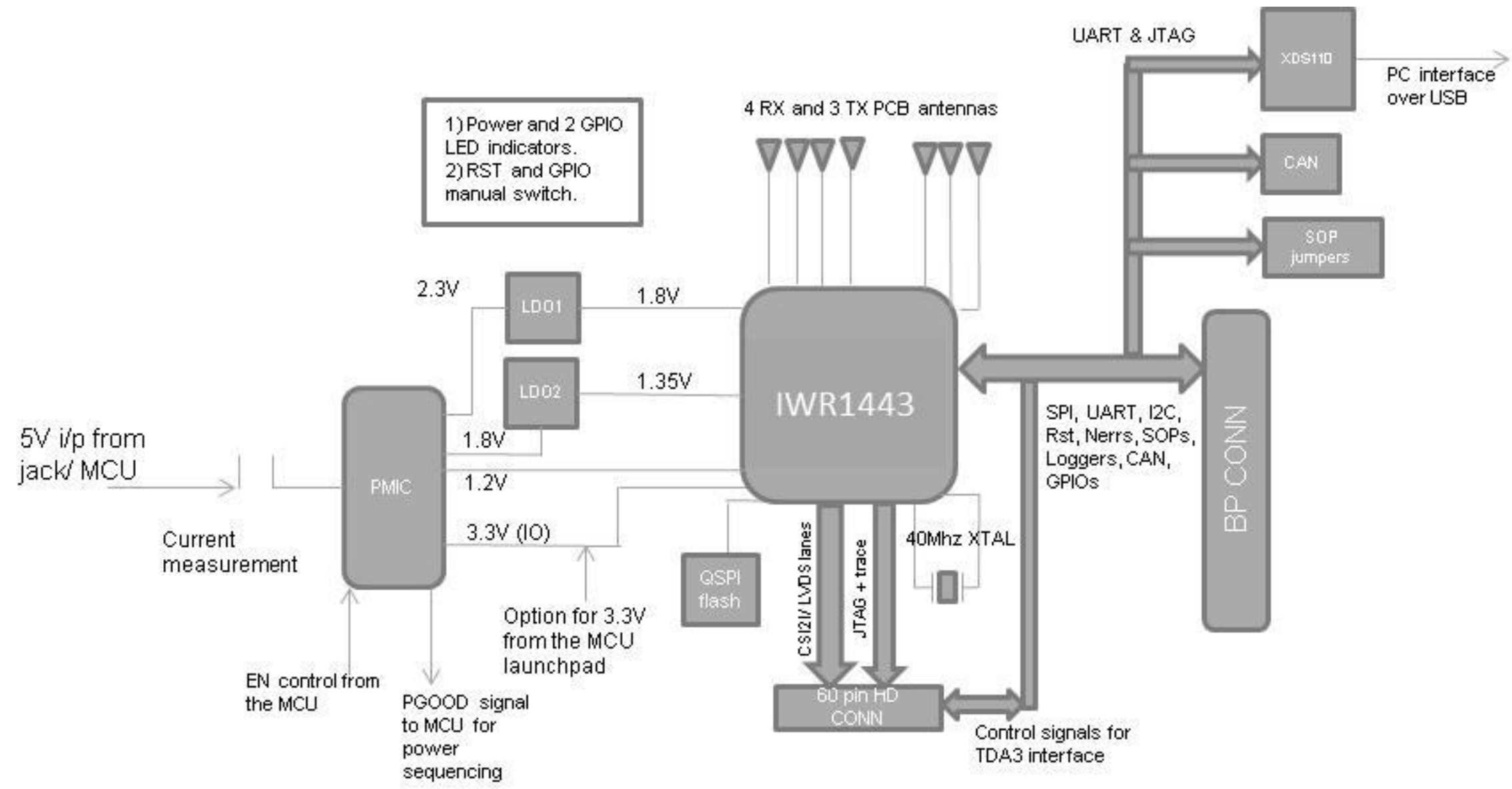
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ASSEMBLY NOTES:
 ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE
 ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED
 COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED

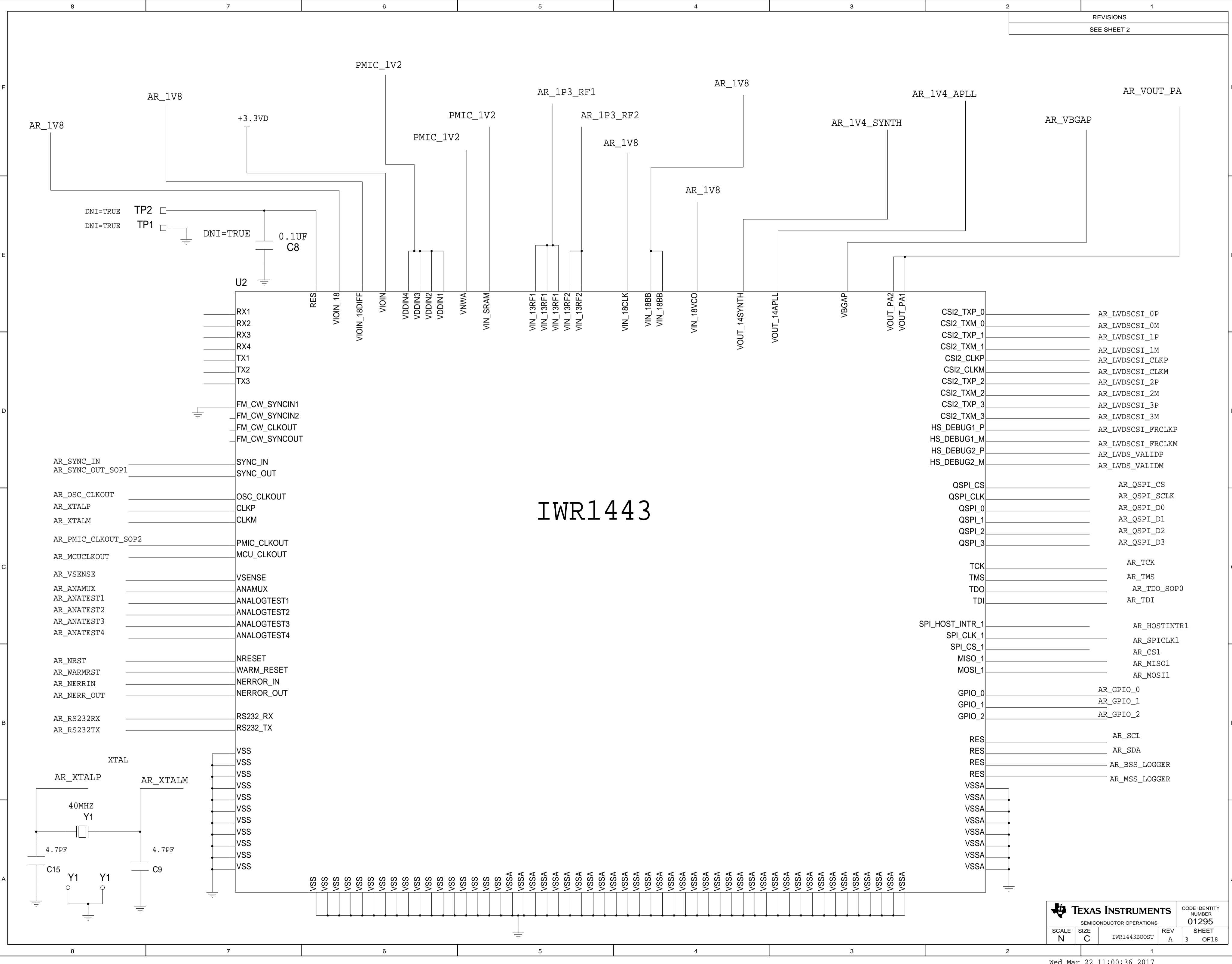
 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		SIZE B
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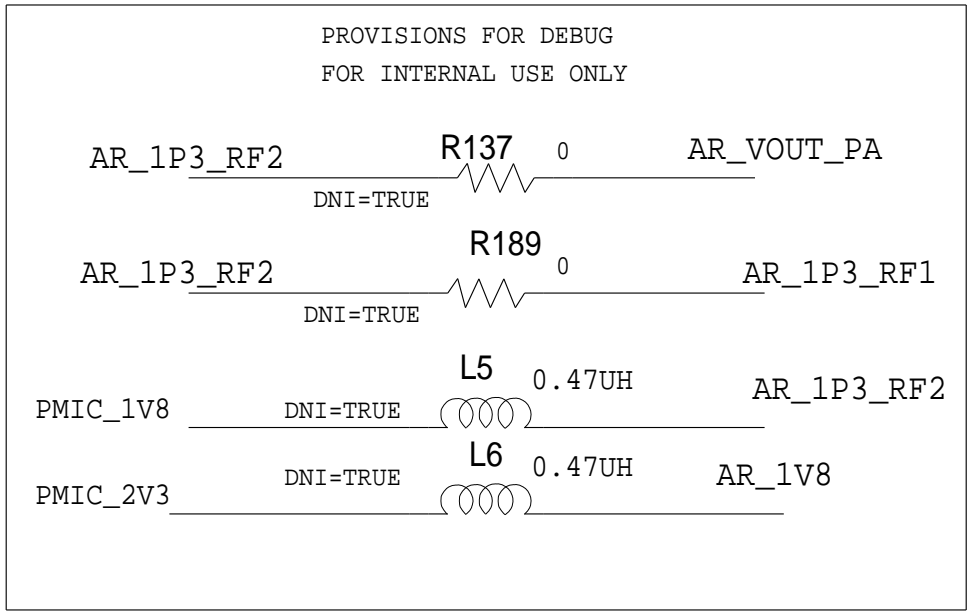
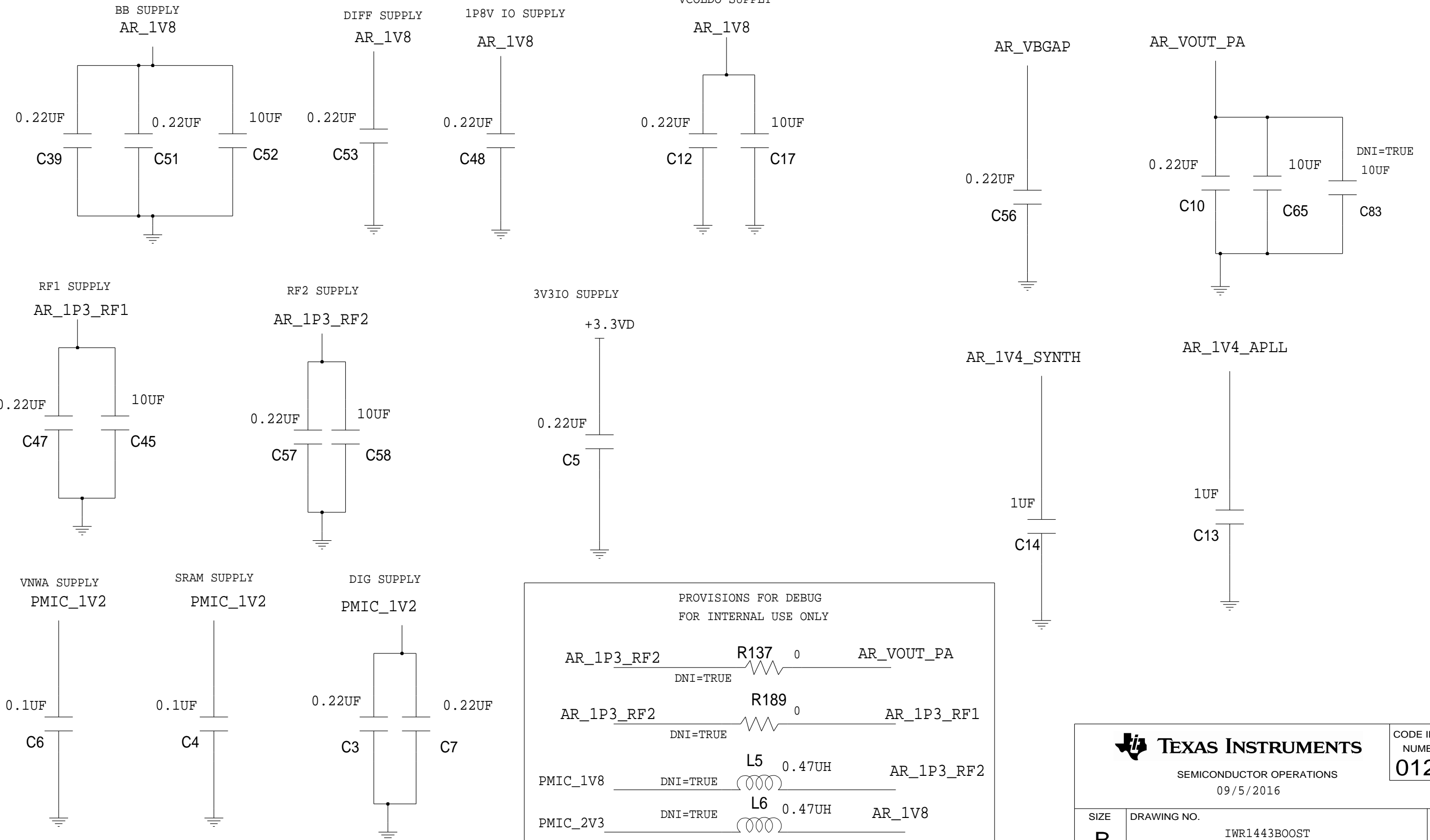
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		SIZE B
Block diagram		SHEET 2 OF 18

IWR1443



SUPPLY_DECOUPLING_CAPS

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DRAWING NO. IWR1443BOOST		REV A
Decoupling caps		SHEET 4 OF 18

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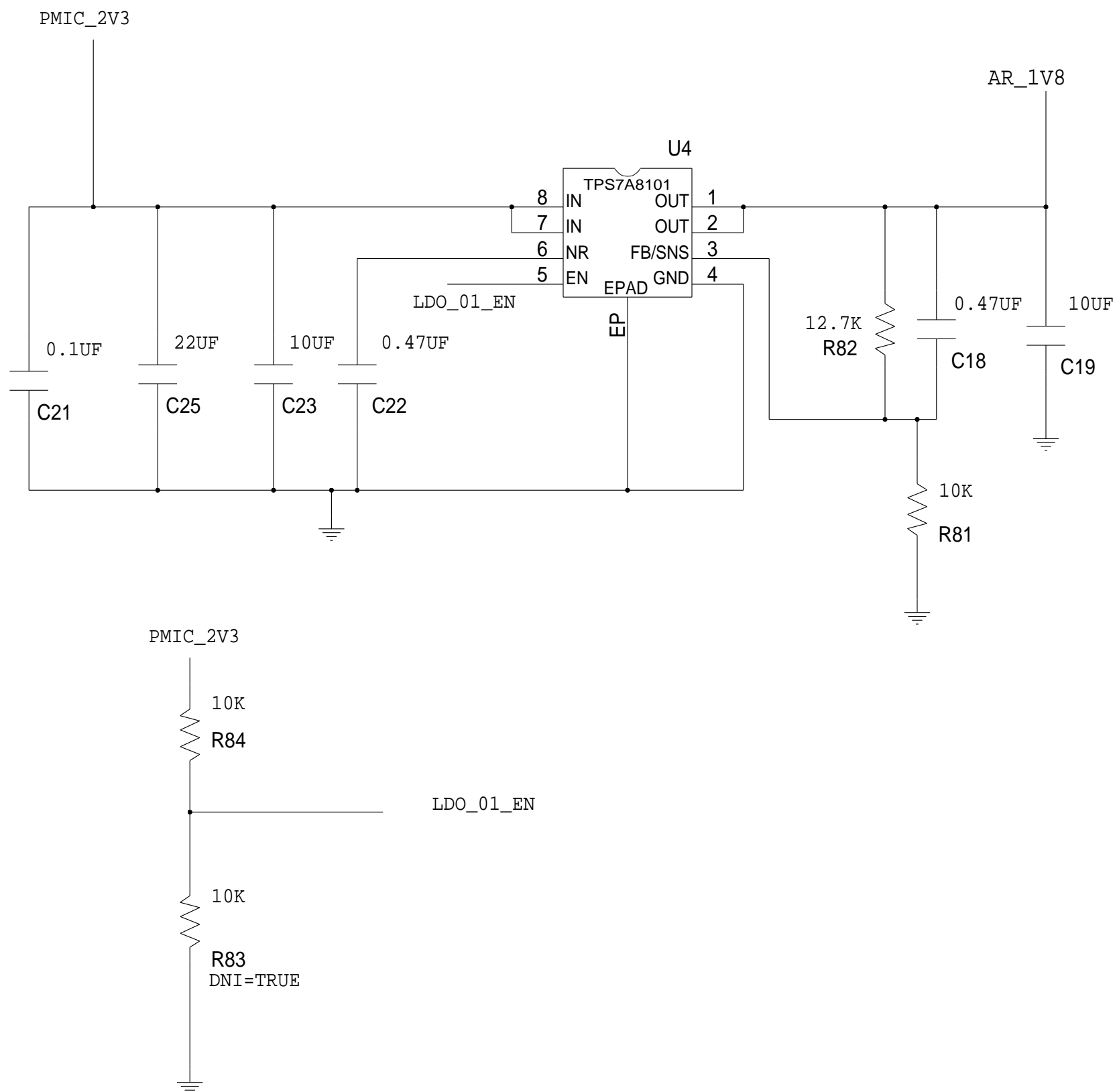
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LDO_01 (1.8V OUTPUT)

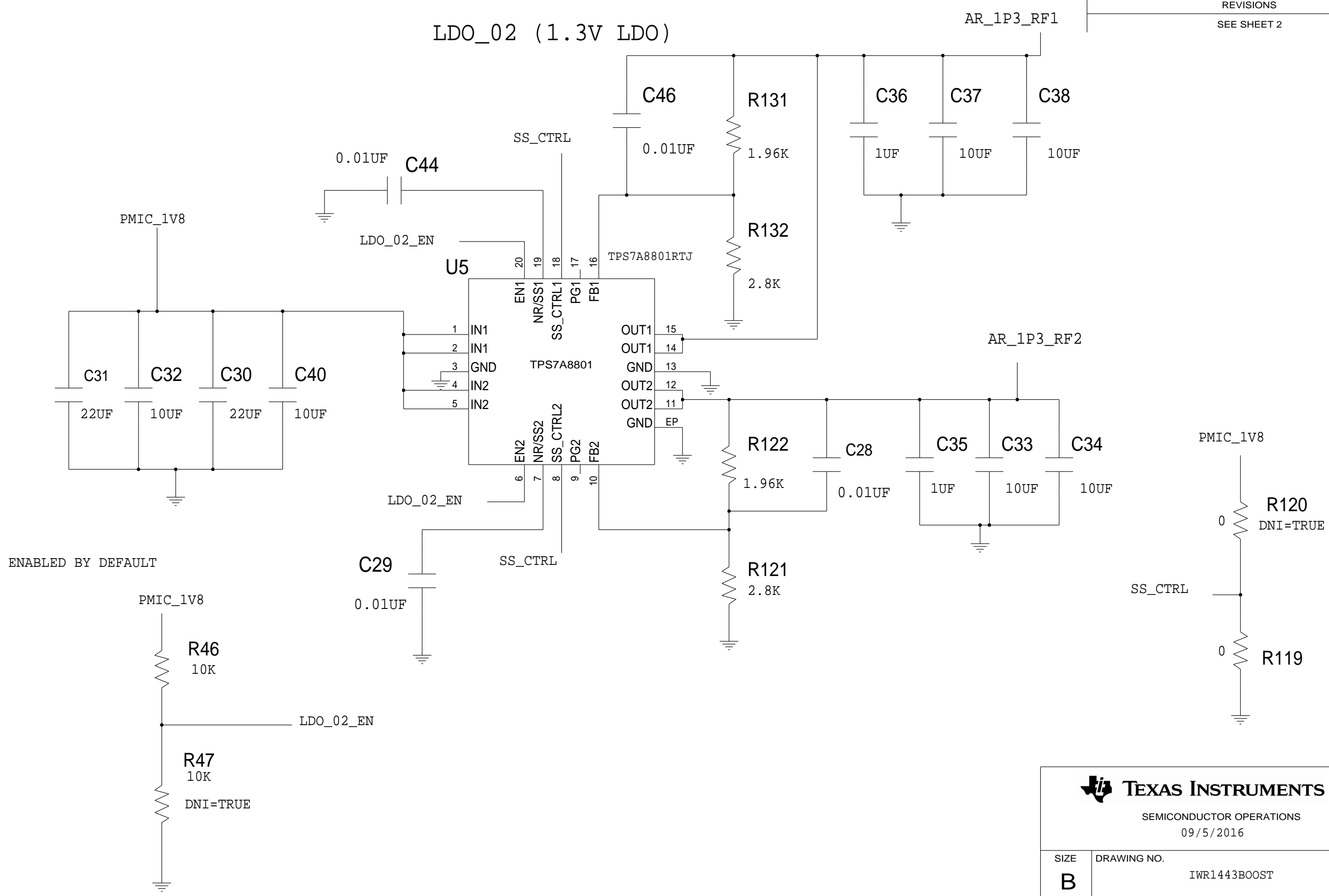
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		SIZE B
LDO_01 (1.8V Output)		SHEET 5 OF 18

LDO_02 (1.3V LDO)

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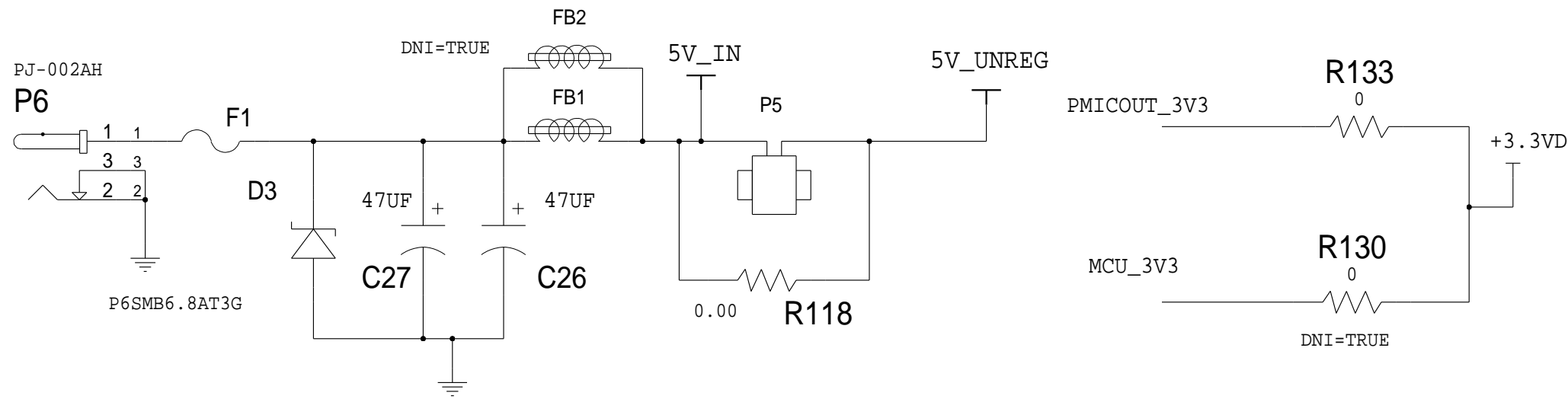


ENABLED BY DEFAULT

TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		SIZE: B DRAWING NO.: IWR1443BOOST REV: A
LDO_02 (1.3V Output)		SHEET 6 OF 18

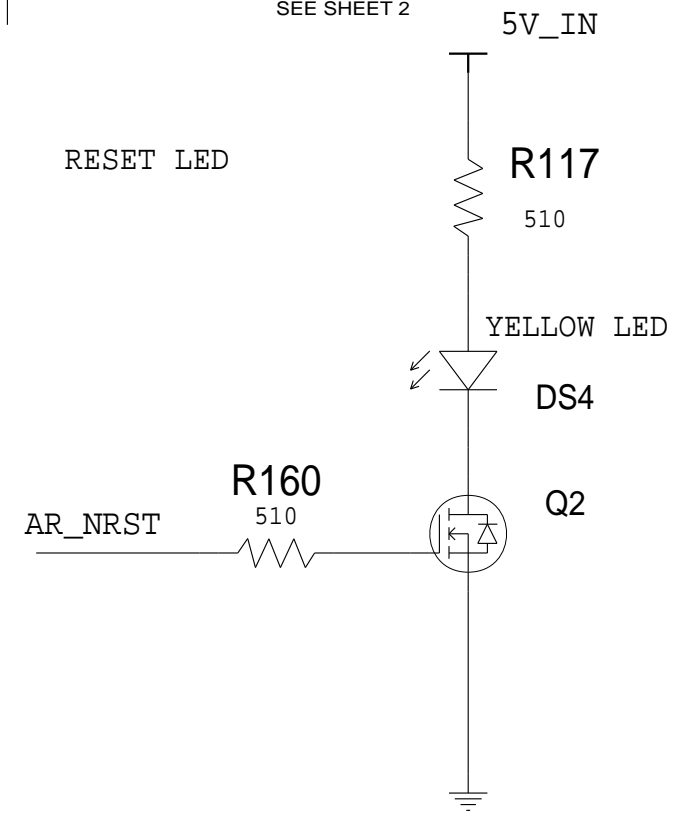
POWER SUPPLY CONNECTOR

3P3 SUPPLY FROM PMIC OR FROM THE MCU



REVISIONS

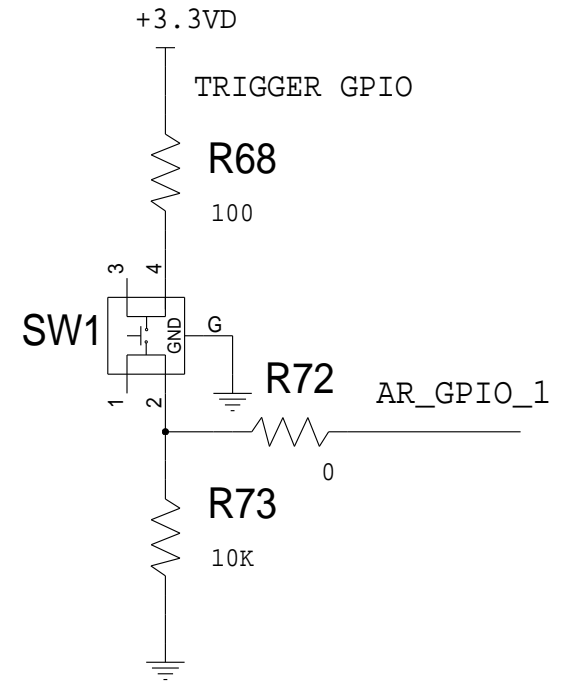
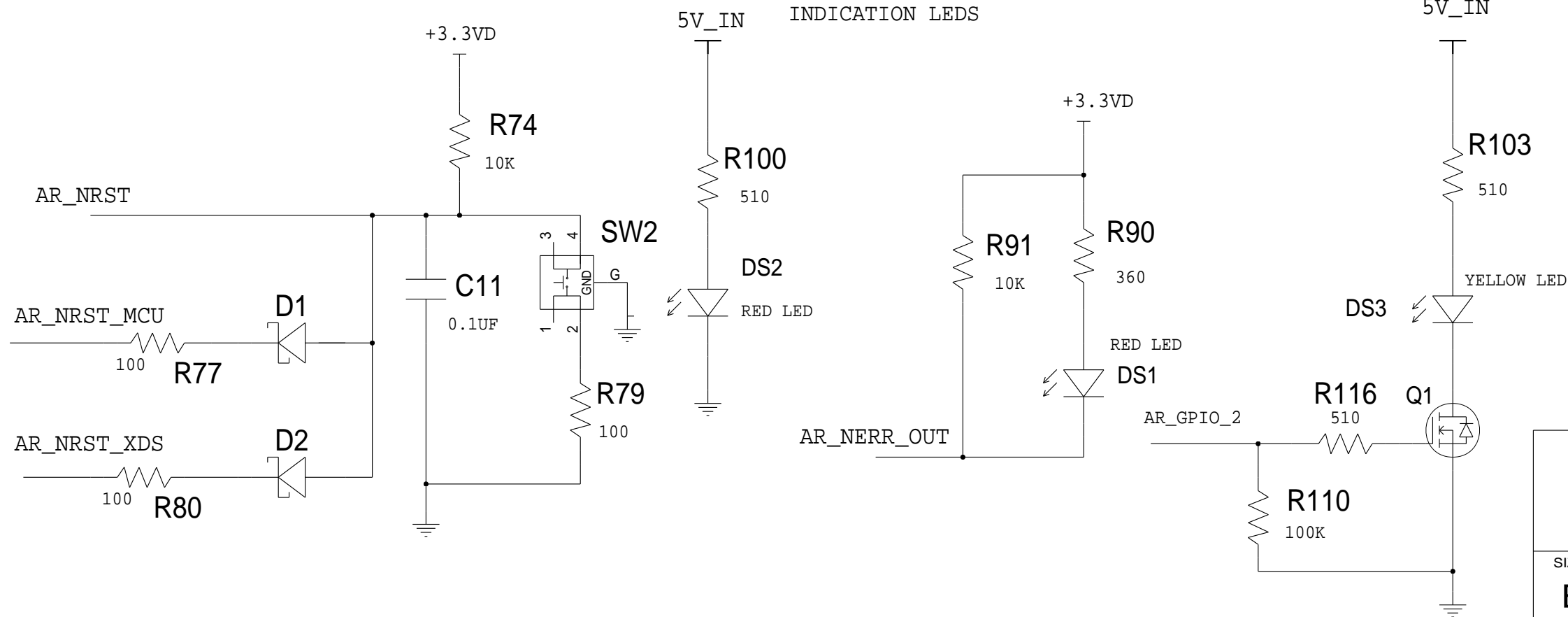
SEE SHEET 2



RESET AND LEDS

SW FOR MANUAL RESET

INDICATION LEDS



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SEMICONDUCTOR OPERATIONS
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Pwr_RST_LEDs

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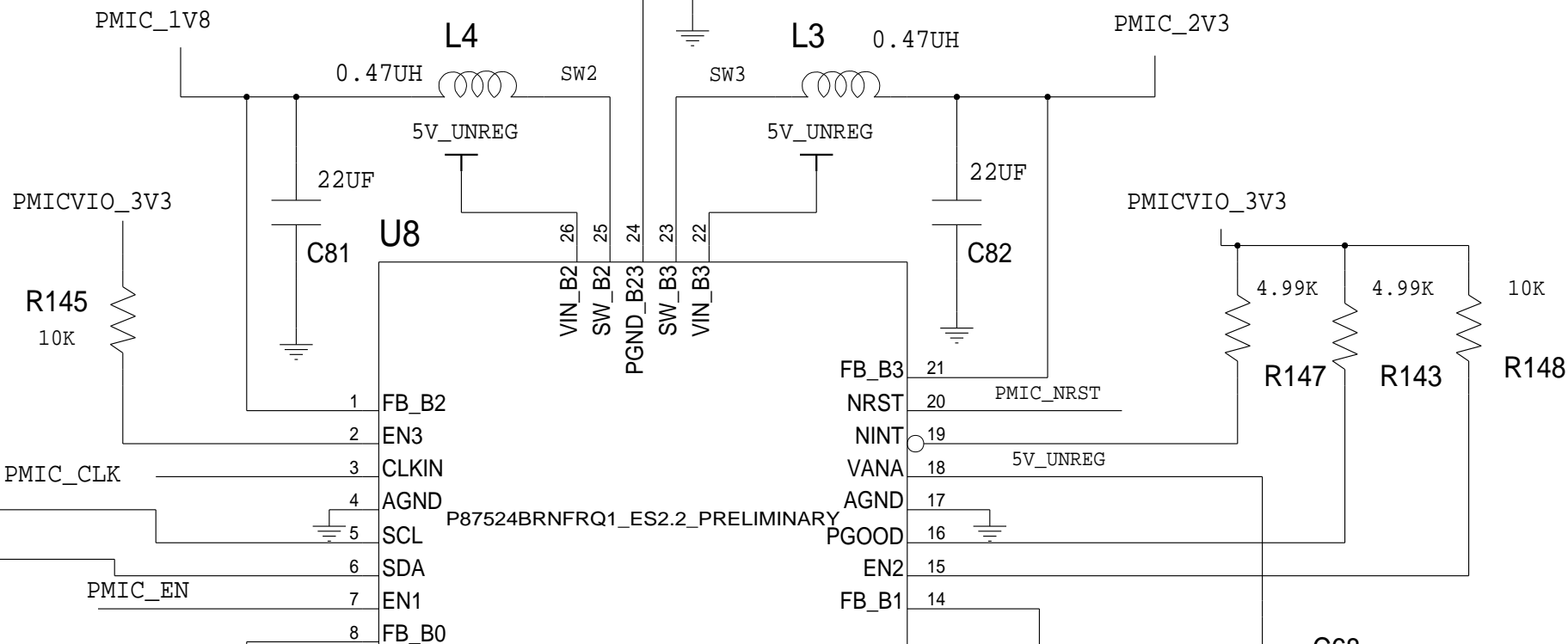
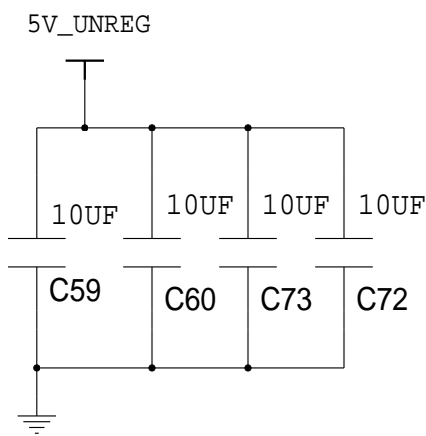
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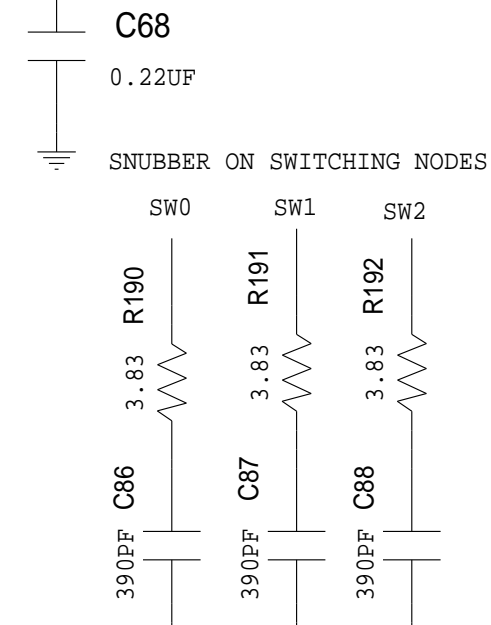
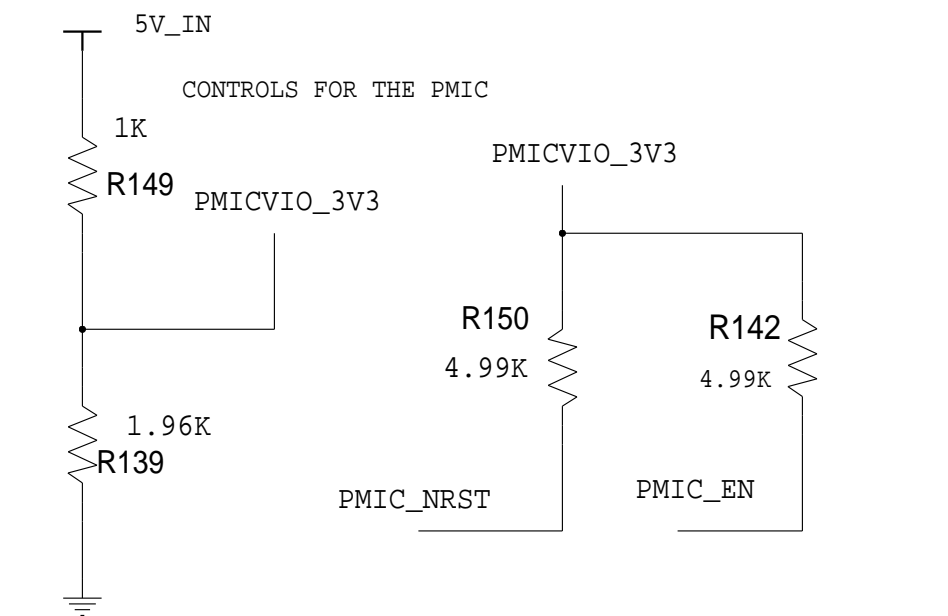
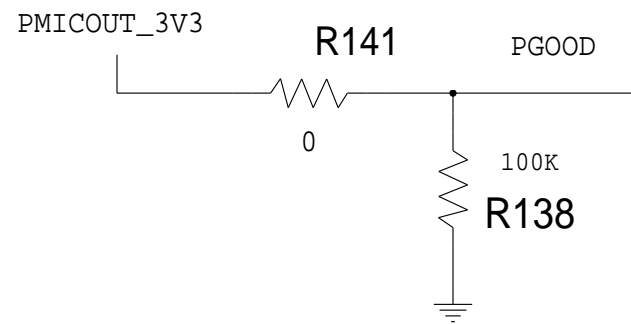
1

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PMIC (3.3V, 1.2V, 1.8V, 2.3V OUTPUTS)



THE 3V3 OUTPUT FROM PMIC IS USED AS PGOOD.



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SEMICONDUCTOR OPERATIONS 09/5/2016		
SIZE B	DRAWING NO. IWR1443BOOST	REV A
PMIC		SHEET 8 OF 18

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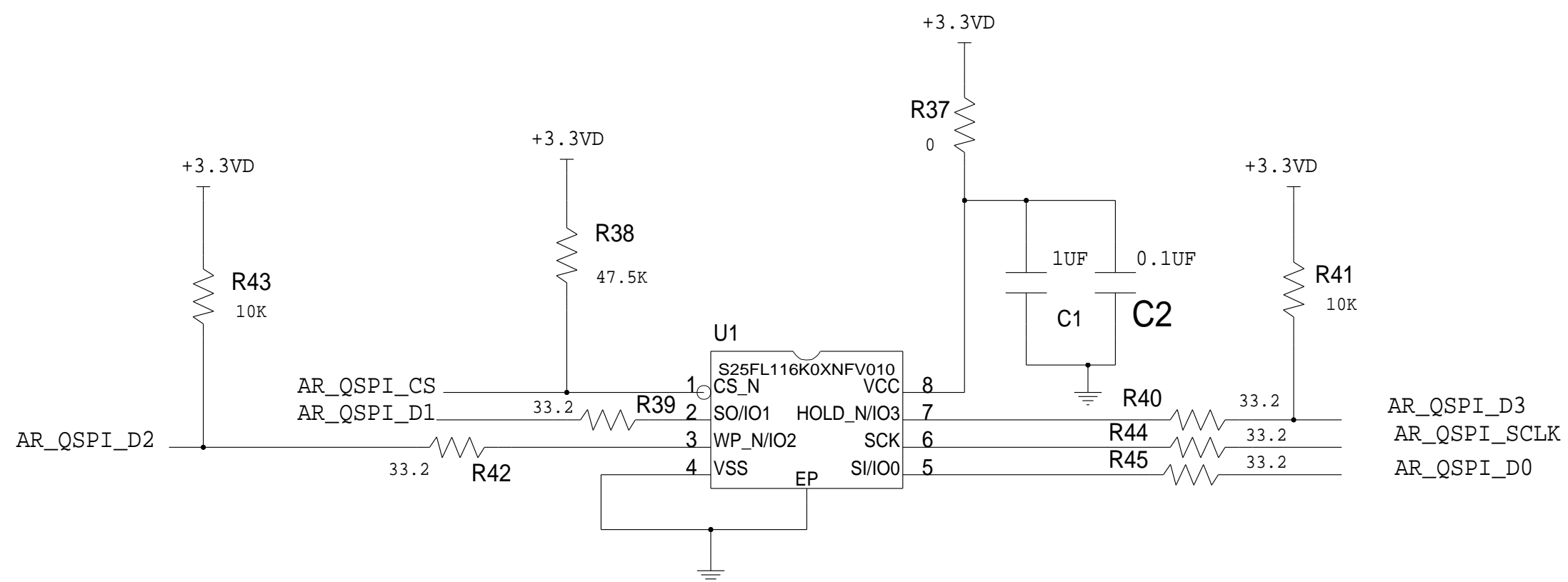
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REVISIONS
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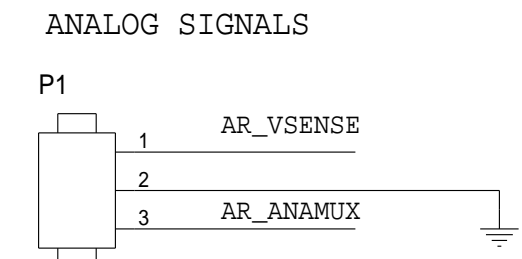
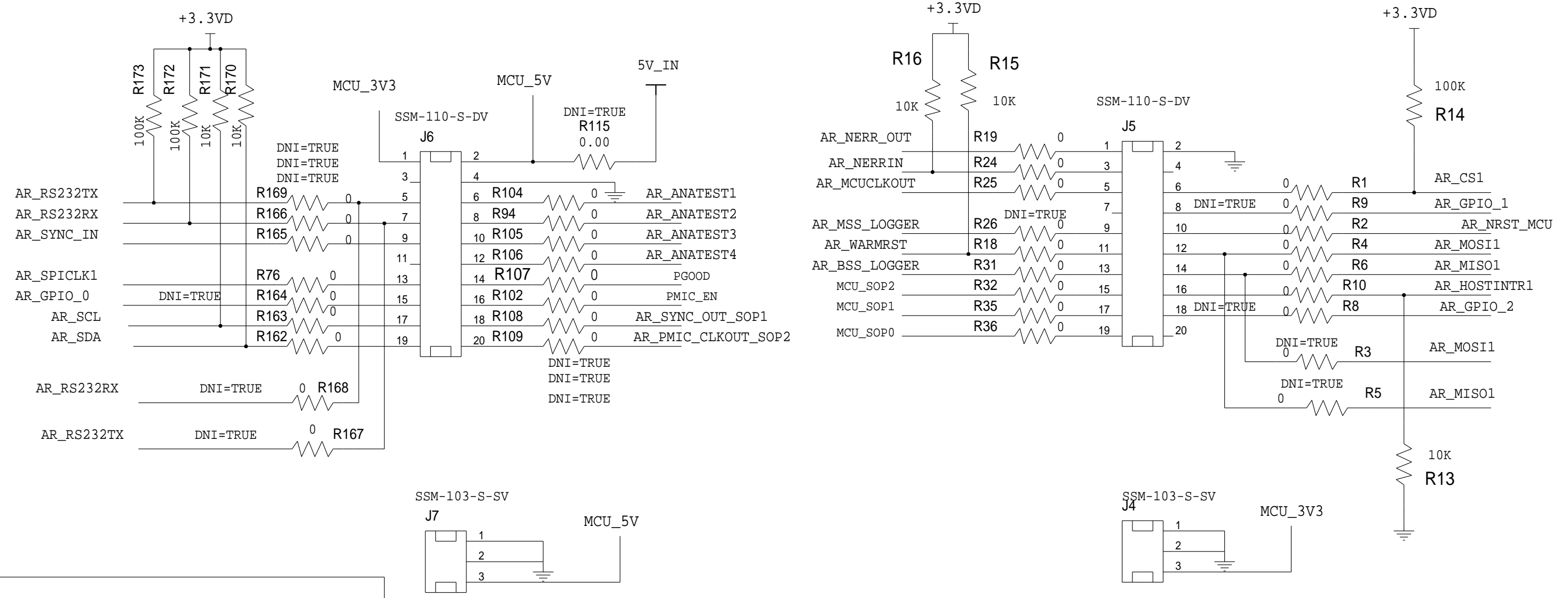
QSPI FLASH



TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		SIZE: B DRAWING NO.: IWR1443BOOST REV: A
Flash Section		SHEET 9 OF 18

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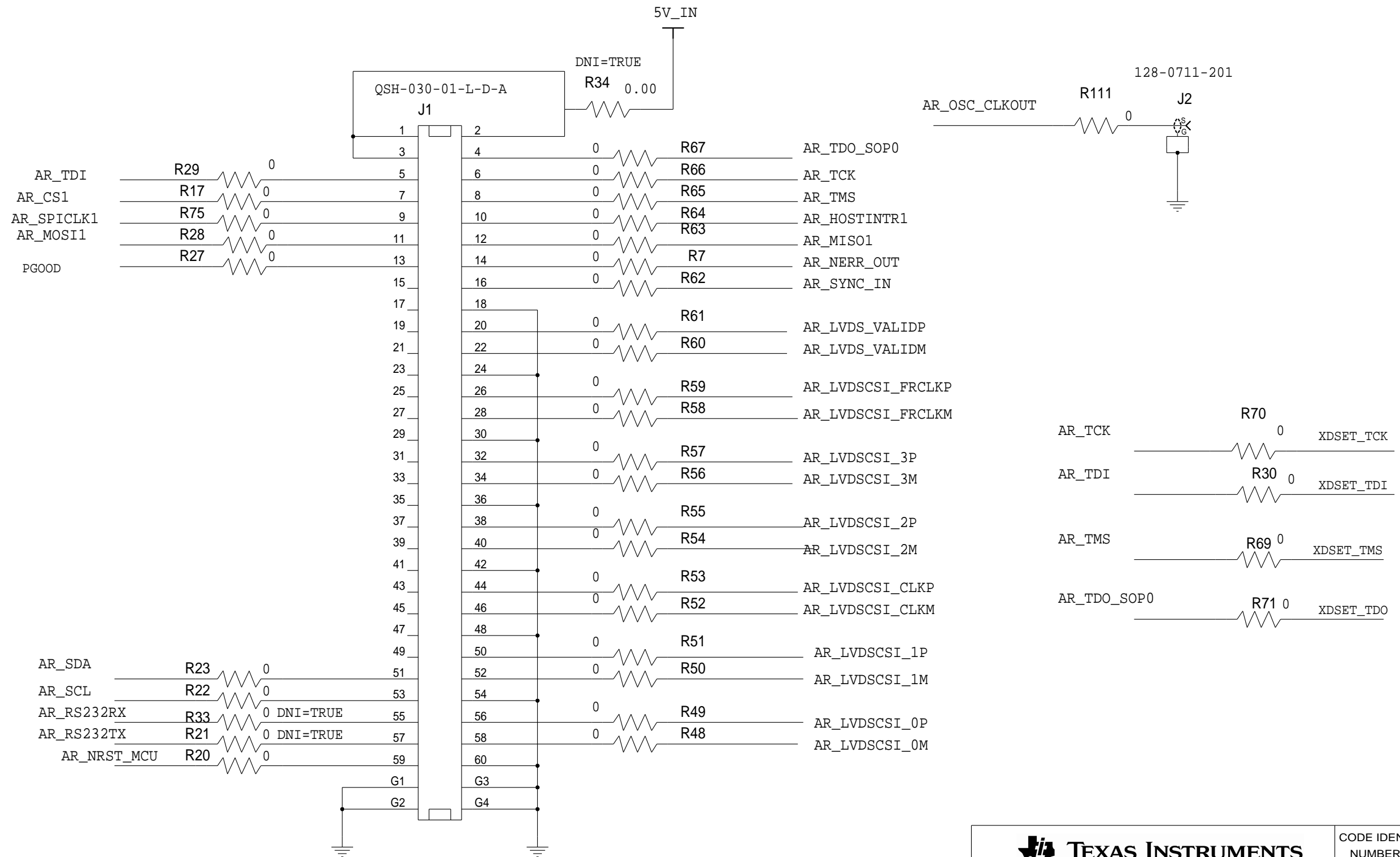
BP/LP CONNECTOR




TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		REV A
SIZE B	DRAWING NO. IWR1443BOOST	SHEET 10 OF 18

HD CONNECTOR FOR LVDS/CSI AND JTAG

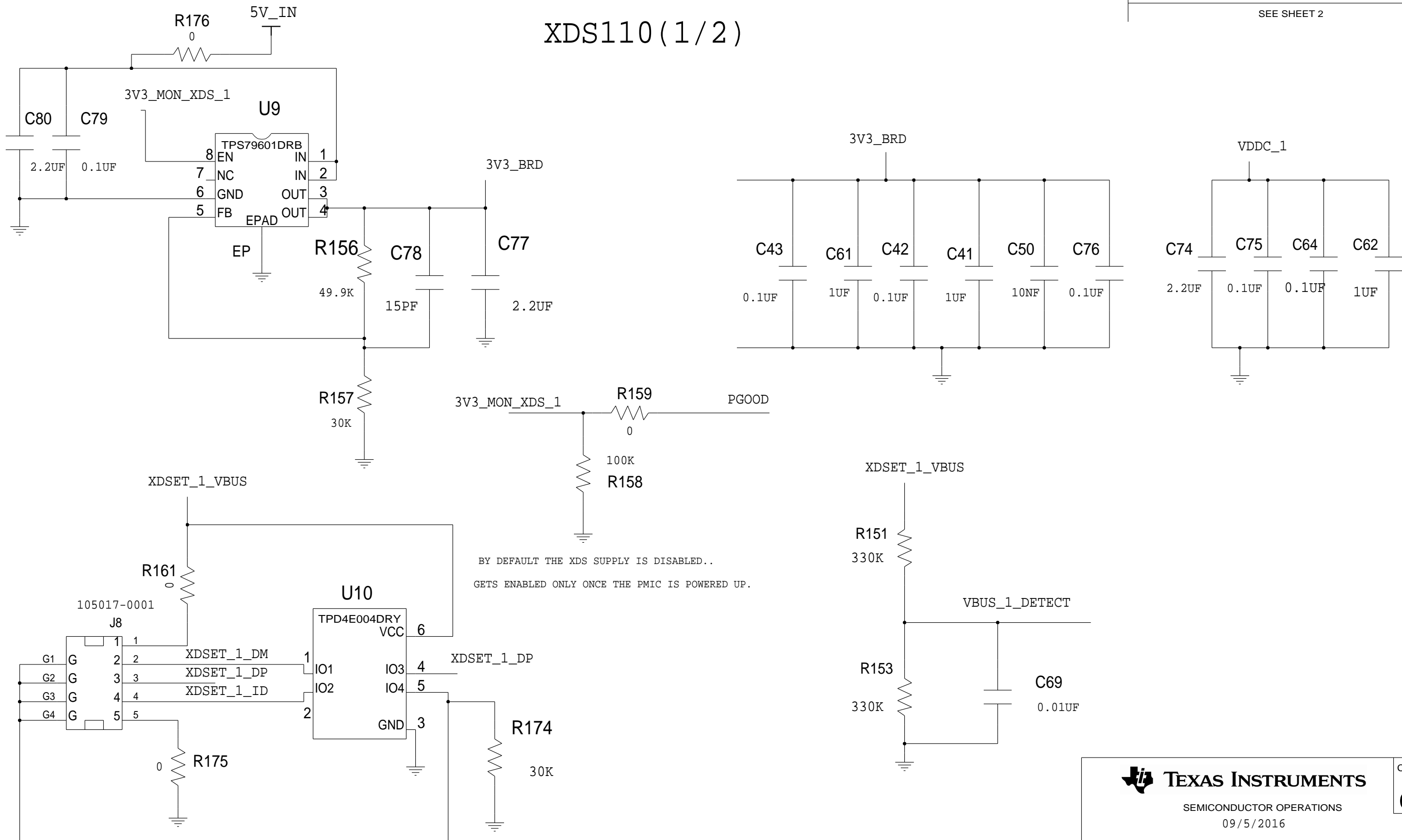
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SEMICONDUCTOR OPERATIONS 09/5/2016		
SIZE B	DRAWING NO. IWR1443BOOST	REV A
HD Connector		SHEET 11 OF 18

XDS110(1/2)

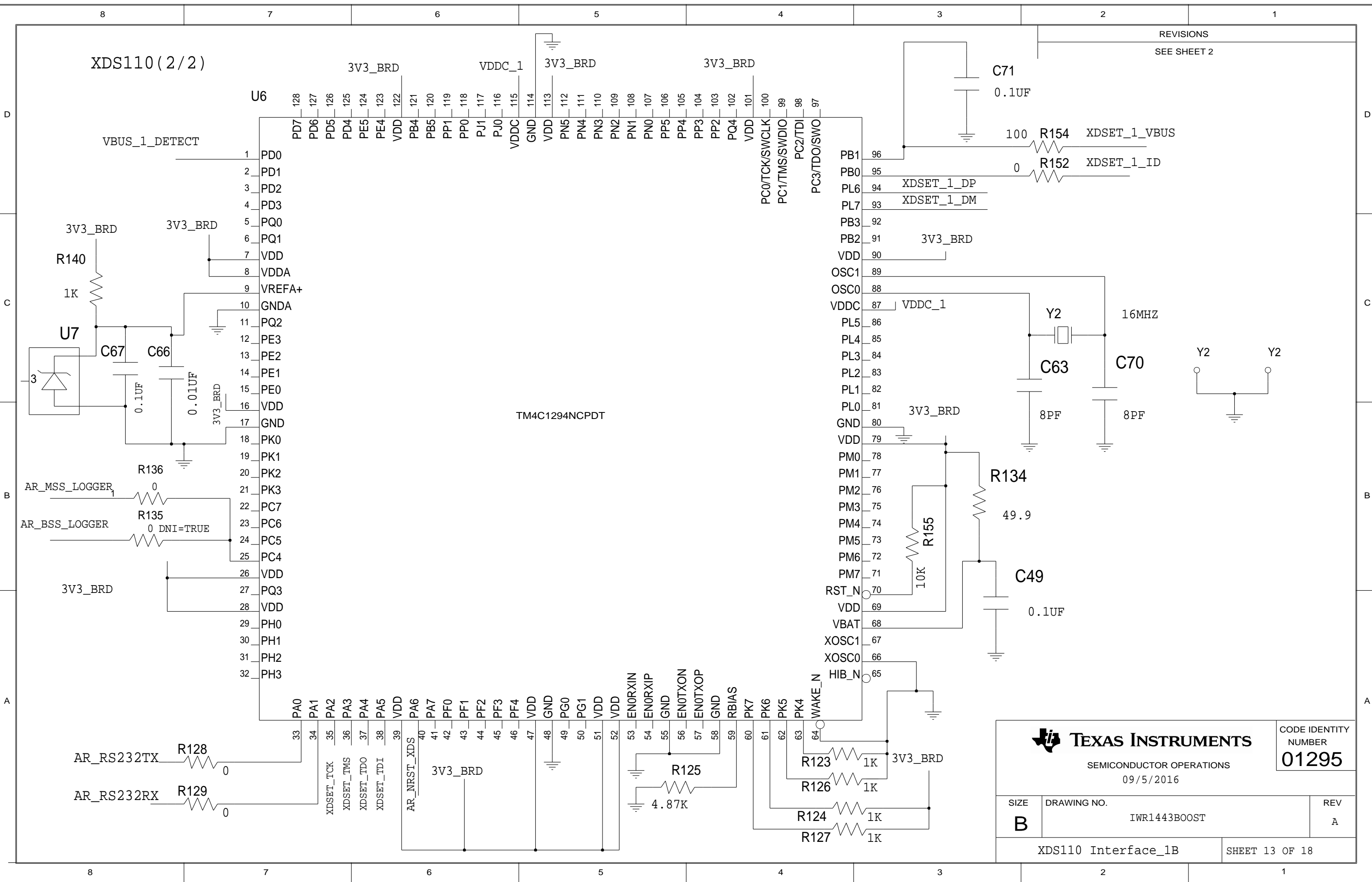
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		SIZE: B DRAWING NO.: IWR1443BOOST REV: A
XDS110 Interface_1A		SHEET 12 OF 18

XDS110 (2/2)

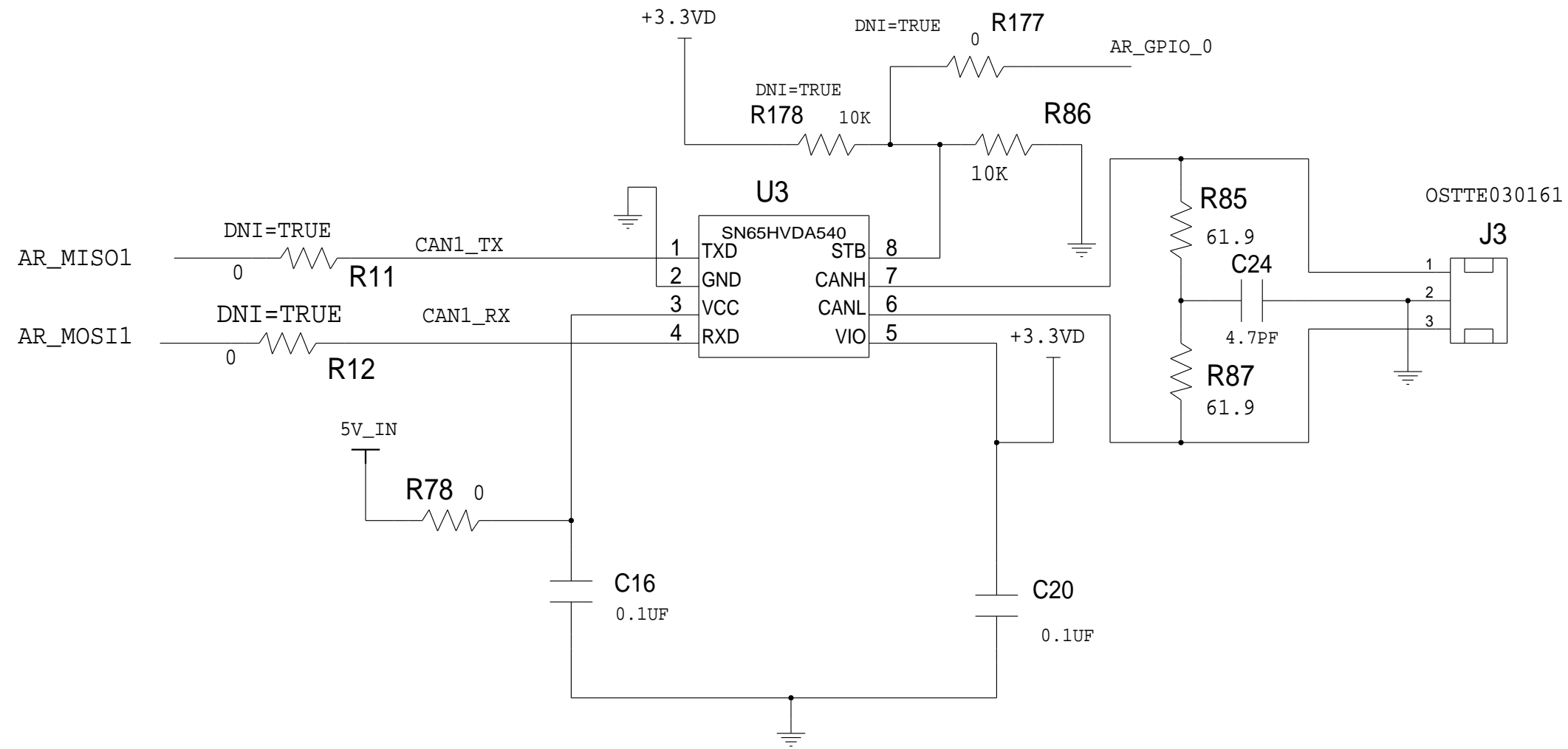
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TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		REV A
SIZE B	DRAWING NO. IWR1443BOOST	SHEET 13 OF 18

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CAN INTERFACE



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		SIZE B
CAN Interface		SHEET 14 OF 18

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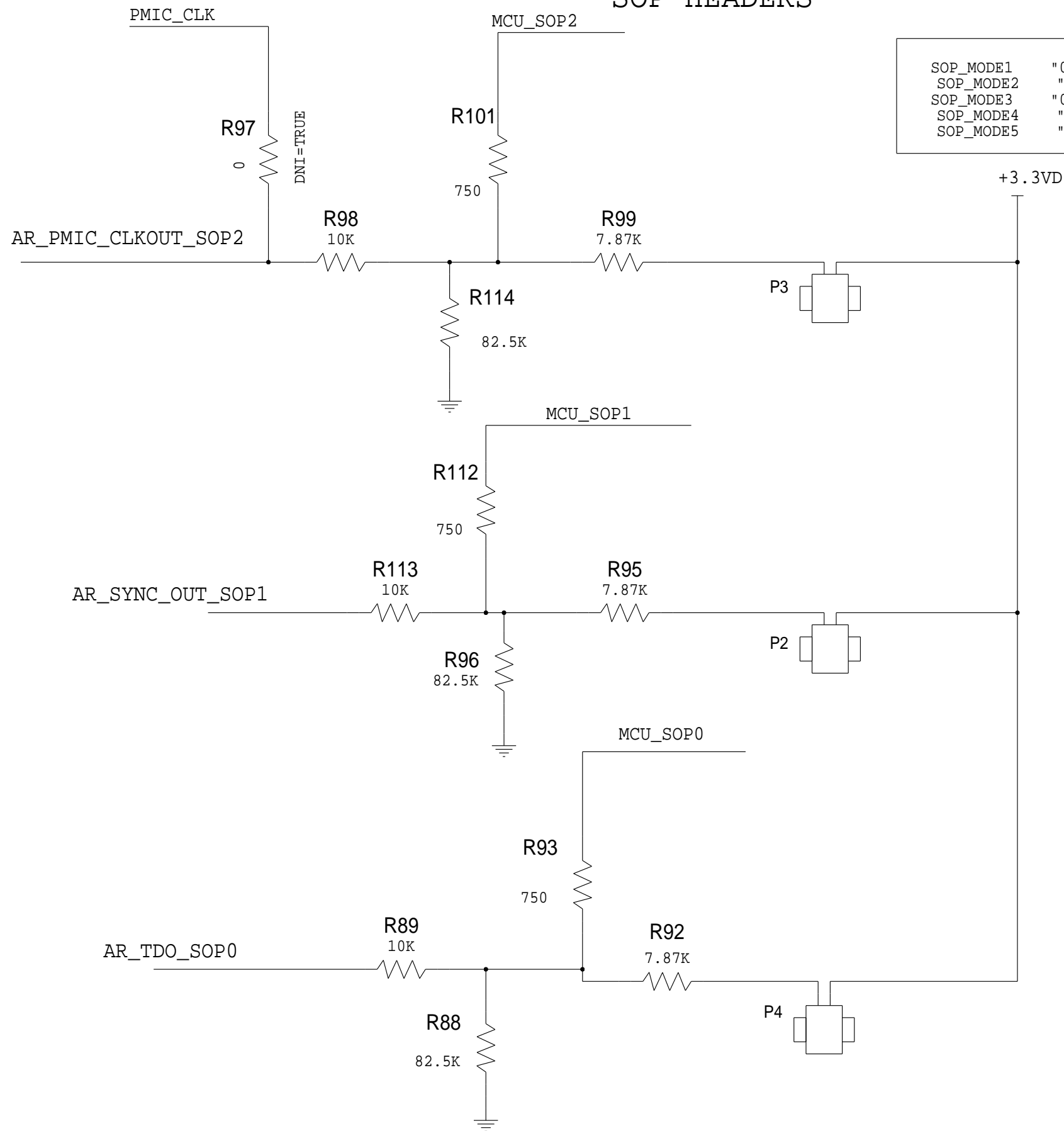
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SOP HEADERS

REVISIONS
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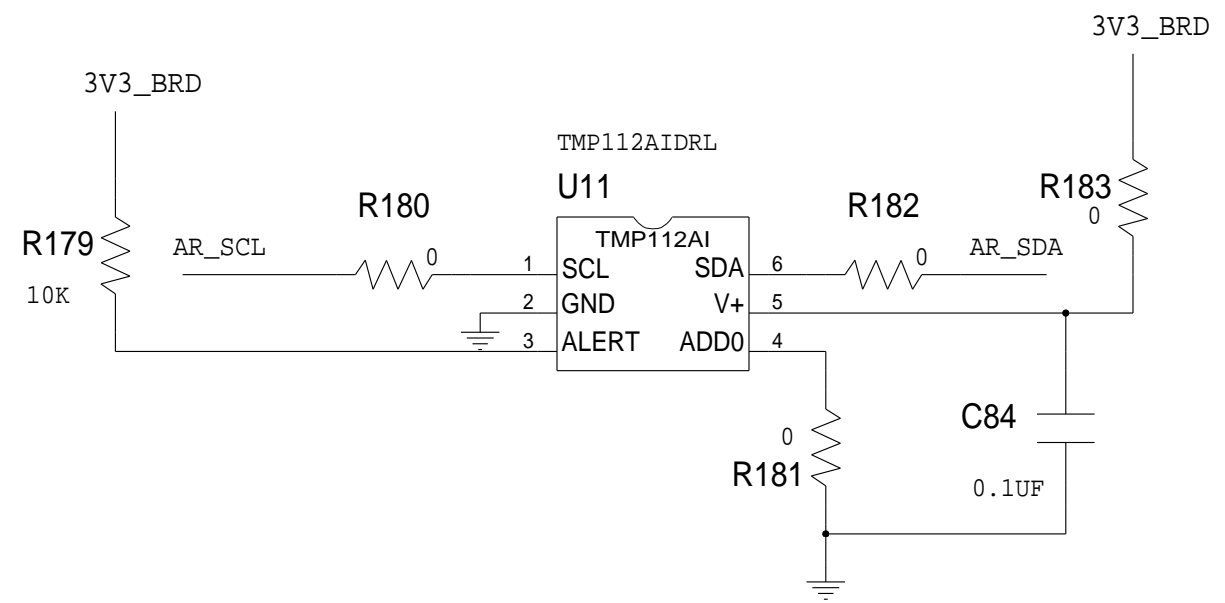
SOP_MODE1	"010"	SCAN/ATPG
SOP_MODE2	"011"	DEV/FLED/ORBIT
SOP_MODE3	"000"	THB
SOP_MODE4	"001"	FUNC - > DEFAULT VALUE FOR OUTPUTS
SOP_MODE5	"101"	DEV MANAGEMENT -> FOR FLASHING



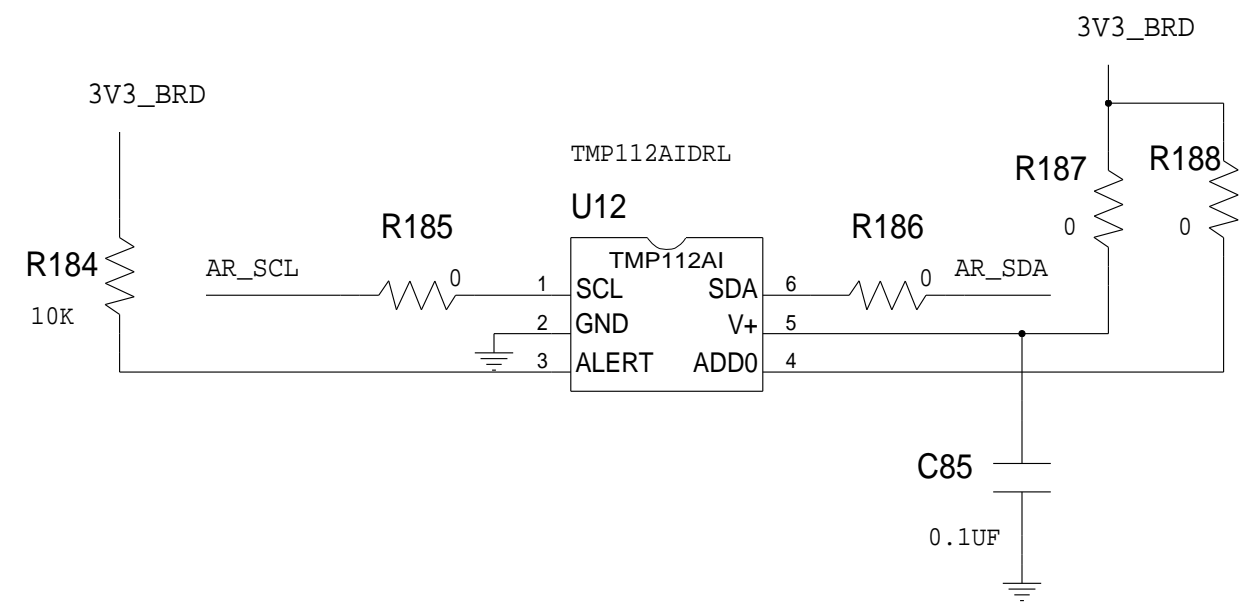
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DRAWING NO. IWR1443BOOST		REV A
SOP selection		SHEET 15 OF 18

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ONBOARD TEMP SENSORS



TEMP SENSOR CLOSE TO PMIC
DEFAULT I2C ADDRESS : 0X48



TEMP SENSOR AWAY FROM PMIC
AND MMWAVE DEVICE
DEFAULT I2C ADDRESS : 0X49

TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS 09/5/2016		CODE IDENTITY NUMBER 01295
		SIZE B
Tempsensor		SHEET 16 OF 18

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REVISION HISTORY

CHANGES IN REV A

- 1) ADDED ZENER DIODE ON 5V INPUT TO PROTECT FROM HIGH VOLTAGES.
- 2) ADDED ONBOARD TEMPERATURE SENSORS.
- 3) ADDED FERRITE BEAD ON 5V SUPPLY.
- 4) CHANGED THE PMIC PART TO PG2.2 VERSION
- 5) ADDED DUMMY ANTENNAS FOR RX
- 6) ADDED PM DUBUG PROVISION FOR LDO BYPASS



TEXAS INSTRUMENTS

SEMICONDUCTOR OPERATIONS
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IWR1443BOOST

REV

A

Revision_History

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REVISIONS
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- FD1
- FD2
- FD3
- FD4
- FD5
- FD6

PCB LOGO

TEXAS INSTRUMENTS

PCB LOGO

ESD SENSITIVE

PCB LOGO

FCC DISCLAIMER

PCB LOGO

LAUNCHPAD COMPATIBLE

PCB LOGO

ROHS EXEMPT

PCB LABELS : THESE LABELS NEED TO BE PUT ON THE ASSEMBLED PCB

- 1) TOP SIDE OF THE PCB -> IWR1443BOOST
REV A
- 2) BOTTOM SIDE OF THE PCB -> IWR1443BOOST
REV A

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NUMBER

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SIZE

B

DRAWING NO.

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REV

A

Hardware

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